- ***EPIC*™ (Enhanced-Performance Implanted CMOS) Submicron Process**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic (N) and Ceramic (J) DIPS**

description

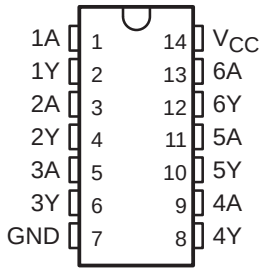
The ’AC14 devices contain six independent inverters. The devices perform the Boolean function $Y = \overline{A}$.

The SN54AC14 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74AC14 is characterized for operation from –40°C to 85°C.

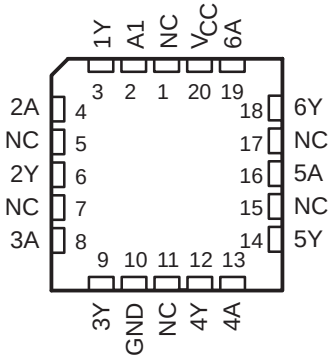
FUNCTION TABLE
(each inverter)

INPUT A	OUTPUT Y
H	L
L	H

SN54AC14 . . . J OR W PACKAGE
SN74AC14 . . . D, DB, N, OR PW PACKAGE
(TOP VIEW)

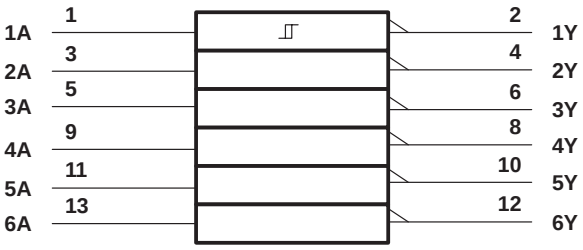


SN54AC14 . . . FK PACKAGE
(TOP VIEW)



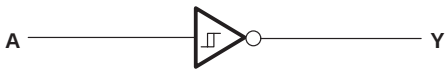
NC – No internal connection

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, DB, J, N, PW, or W packages.

logic diagram, each inverter (positive logic)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC is a trademark of Texas Instruments Incorporated.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . – 0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) . . . . . –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) . . . . . ± 20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) . . . . . ± 20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . . ± 50 mA
Continuous current through V_{CC} or GND . . . . . ± 200 mA
Package thermal impedance, θ_{JA} (see Note 2): D package . . . . . 127°C/W
DB package . . . . . 158°C/W
N package . . . . . 78°C/W
PW package . . . . . 170°C/W
Storage temperature range, T_{stg} . . . . . – 65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero

recommended operating conditions (see Note 3)

			SN54AC14		SN74AC14		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		–12		–12	mA
		V_{CC} = 4.5 V		–24		–24	
		V_{CC} = 5.5 V		–24		–24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54AC14		SN74AC14		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{T+} Positive-going threshold		3 V	0.8	1.8	2.2	0.8	2.2	0.8	2.2	V
		4.5 V	1.5	2.6	3.2	1.5	3.2	1.5	3.2	
		5.5 V	1.6	3.2	3.9	1.6	3.9	1.6	3.9	
V_{T-} Negative-going threshold		3 V	0.5	0.8	1	0.5	1	0.5	1	V
		4.5 V	0.9	1.4	1.8	0.9	1.8	0.9	1.8	
		5.5 V	1.1	1.8	2.3	1.1	2.3	1.1	2.3	
ΔV_T Hysteresis ($V_{T+} - V_{T-}$)		3 V	0.3	1	1.2	0.3	1.2	0.3	1.2	V
		4.5 V	0.4	1.2	1.4	0.4	1.4	0.4	1.4	
		5.5 V	0.5	1.4	1.6	0.5	1.6	0.5	1.6	
V_{OH}	I_{OH} = – 50 µA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = – 12 mA	3 V	2.56			2.4		2.48		
	I_{OH} = – 24 mA	4.5 V	3.86			3.7		3.8		
		5.5 V	4.86			4.7		4.8		
	I_{OH} = – 50 mA†	5.5 V				3.85				
	I_{OH} = – 75 mA†	5.5 V						3.85		
V_{OL}	I_{OL} = 50 µA	3 V		0.002	0.1		0.1		0.1	V
		4.5 V		0.001	0.1		0.1		0.1	
		5.5 V		0.001	0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA†	5.5 V					1.65			
	I_{OL} = 75 mA†	5.5 V							1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			2		40		20	µA
C_i	$V_I = V_{CC}$ or GND	5 V		4.5						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC14		SN74AC14		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	6	13.5	1	16	1.5	15	ns
t_{PHL}			1.5	6	11.5	1	14	1.5	13	

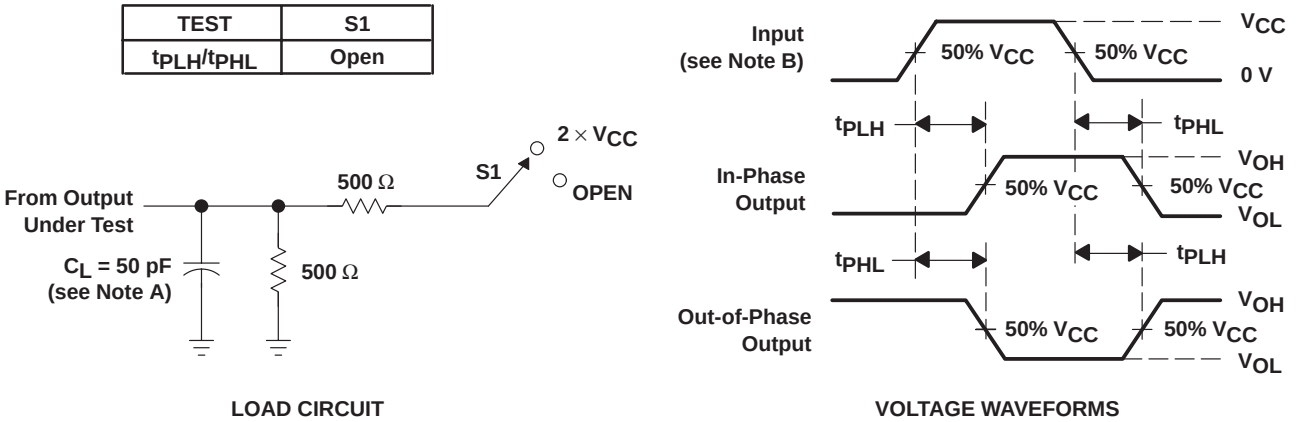
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC14		SN74AC14		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	5	10	1.5	12	1.5	11	ns
t_{PHL}			1.5	5	8.5	1.5	10	1.5	9.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	25	pF

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT **VOLTAGE WAVEFORMS**

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.